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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Active
Number of LABs/CLBs	2816
Number of Logic Elements/Cells	25344
Total RAM Bits	589824
Number of I/O	161
Number of Gates	1400000
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	256-LBGA
Supplier Device Package	256-FTBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc3s1400a-4ftg256i

General DC Characteristics for I/O Pins

Table 9: General DC Characteristics of User I/O, Dual-Purpose, and Dedicated Pins⁽¹⁾

Symbol	Description	Test Conditions		Min	Typ	Max	Units
$I_L^{(2)}$	Leakage current at User I/O, input-only, dual-purpose, and dedicated pins, FPGA powered	Driver is in a high-impedance state, $V_{IN} = 0V$ or V_{CCO} max, sample-tested		-10	—	+10	μA
I_{HS}	Leakage current on pins during hot socketing, FPGA unpowered	All pins except INIT_B, PROG_B, DONE, and JTAG pins when PUDC_B = 1.		-10	—	+10	μA
		INIT_B, PROG_B, DONE, and JTAG pins or other pins when PUDC_B = 0.		Add $I_{HS} + I_{RPU}$			μA
$I_{RPU}^{(3)}$	Current through pull-up resistor at User I/O, dual-purpose, input-only, and dedicated pins. Dedicated pins are powered by V_{CCAUX} .	$V_{IN} = GND$	V_{CCO} or $V_{CCAUX} = 3.0V$ to $3.6V$	-151	-315	-710	μA
			V_{CCO} or $V_{CCAUX} = 2.3V$ to $2.7V$	-82	-182	-437	μA
			$V_{CCO} = 1.7V$ to $1.9V$	-36	-88	-226	μA
			$V_{CCO} = 1.4V$ to $1.6V$	-22	-56	-148	μA
			$V_{CCO} = 1.14V$ to $1.26V$	-11	-31	-83	μA
$R_{PU}^{(3)}$	Equivalent pull-up resistor value at User I/O, dual-purpose, input-only, and dedicated pins (based on I_{RPU} per Note 3)	$V_{IN} = GND$	$V_{CCO} = 3.0V$ to $3.6V$	5.1	11.4	23.9	$k\Omega$
			$V_{CCO} = 2.3V$ to $2.7V$	6.2	14.8	33.1	$k\Omega$
			$V_{CCO} = 1.7V$ to $1.9V$	8.4	21.6	52.6	$k\Omega$
			$V_{CCO} = 1.4V$ to $1.6V$	10.8	28.4	74.0	$k\Omega$
			$V_{CCO} = 1.14V$ to $1.26V$	15.3	41.1	119.4	$k\Omega$
$I_{RPD}^{(3)}$	Current through pull-down resistor at User I/O, dual-purpose, input-only, and dedicated pins. Dedicated pins are powered by V_{CCAUX} .	$V_{IN} = V_{CCO}$	$V_{CCAUX} = 3.0V$ to $3.6V$	167	346	659	μA
			$V_{CCAUX} = 2.25V$ to $2.75V$	100	225	457	μA
$R_{PD}^{(3)}$	Equivalent pull-down resistor value at User I/O, dual-purpose, input-only, and dedicated pins (based on I_{RPD} per Note 3)	$V_{CCAUX} = 3.0V$ to $3.6V$	$V_{IN} = 3.0V$ to $3.6V$	5.5	10.4	20.8	$k\Omega$
			$V_{IN} = 2.3V$ to $2.7V$	4.1	7.8	15.7	$k\Omega$
			$V_{IN} = 1.7V$ to $1.9V$	3.0	5.7	11.1	$k\Omega$
			$V_{IN} = 1.4V$ to $1.6V$	2.7	5.1	9.6	$k\Omega$
			$V_{IN} = 1.14V$ to $1.26V$	2.4	4.5	8.1	$k\Omega$
		$V_{CCAUX} = 2.25V$ to $2.75V$	$V_{IN} = 3.0V$ to $3.6V$	7.9	16.0	35.0	$k\Omega$
			$V_{IN} = 2.3V$ to $2.7V$	5.9	12.0	26.3	$k\Omega$
			$V_{IN} = 1.7V$ to $1.9V$	4.2	8.5	18.6	$k\Omega$
			$V_{IN} = 1.4V$ to $1.6V$	3.6	7.2	15.7	$k\Omega$
			$V_{IN} = 1.14V$ to $1.26V$	3.0	6.0	12.5	$k\Omega$
I_{REF}	V_{REF} current per pin	All V_{CCO} levels		-10	—	+10	μA
C_{IN}	Input capacitance	—		—	—	10	pF
R_{DT}	Resistance of optional differential termination circuit within a differential I/O pair. Not available on Input-only pairs.	$V_{CCO} = 3.3V \pm 10\%$	LVDS_33, MINI_LVDS_33, RSDS_33	90	100	115	Ω
		$V_{CCO} = 2.5V \pm 10\%$	LVDS_25, MINI_LVDS_25, RSDS_25	90	110	—	Ω

Notes:

1. The numbers in this table are based on the conditions set forth in Table 8.
2. For single-ended signals that are placed on a differential-capable I/O, V_{IN} of $-0.2V$ to $-0.5V$ is supported but can cause increased leakage between the two pins. See "Parasitic Leakage" in [UG331, Spartan-3 Generation FPGA User Guide](#).
3. This parameter is based on characterization. The pull-up resistance $R_{PU} = V_{CCO} / I_{RPU}$. The pull-down resistance $R_{PD} = V_{IN} / I_{RPD}$.

Quiescent Current Requirements

Table 10: Quiescent Supply Current Characteristics

Symbol	Description	Device	Typical ⁽²⁾	Commercial Maximum ⁽²⁾	Industrial Maximum ⁽²⁾	Units
I_{CCINTQ}	Quiescent V_{CCINT} supply current	XC3S50A	2	20	30	mA
		XC3S200A	7	50	70	mA
		XC3S400A	10	85	125	mA
		XC3S700A	13	120	185	mA
		XC3S1400A	24	220	310	mA
I_{CCOQ}	Quiescent V_{CCO} supply current	XC3S50A	0.2	2	3	mA
		XC3S200A	0.2	2	3	mA
		XC3S400A	0.3	3	4	mA
		XC3S700A	0.3	3	4	mA
		XC3S1400A	0.3	3	4	mA
I_{CCAUXQ}	Quiescent V_{CCAUX} supply current	XC3S50A	3	8	10	mA
		XC3S200A	5	12	15	mA
		XC3S400A	5	18	24	mA
		XC3S700A	6	28	34	mA
		XC3S1400A	10	50	58	mA

Notes:

- The numbers in this table are based on the conditions set forth in [Table 8](#).
- Quiescent supply current is measured with all I/O drivers in a high-impedance state and with all pull-up/pull-down resistors at the I/O pads disabled. Typical values are characterized using typical devices at room temperature (T_J of 25°C at $V_{CCINT} = 1.2V$, $V_{CCO} = 3.3V$, and $V_{CCAUX} = 2.5V$). The maximum limits are tested for each device at the respective maximum specified junction temperature and at maximum voltage limits with $V_{CCINT} = 1.26V$, $V_{CCO} = 3.6V$, and $V_{CCAUX} = 3.6V$. The FPGA is programmed with a “blank” configuration data file (that is, a design with no functional elements instantiated). For conditions other than those described above (for example, a design including functional elements), measured quiescent current levels will be different than the values in the table.
- For more accurate estimates for a specific design, use the Xilinx XPower tools. There are two recommended ways to estimate the total power consumption (quiescent plus dynamic) for a specific design: a) The [Spartan-3A FPGA XPower Estimator](#) provides quick, approximate, typical estimates, and does not require a netlist of the design. b) XPower Analyzer uses a netlist as input to provide maximum estimates as well as more accurate typical estimates.
- The maximum numbers in this table indicate the minimum current each power rail requires in order for the FPGA to power-on successfully.
- For information on the power-saving Suspend mode, see [XAPP480: Using Suspend Mode in Spartan-3 Generation FPGAs](#). Suspend mode typically saves 40% total power consumption compared to quiescent current.

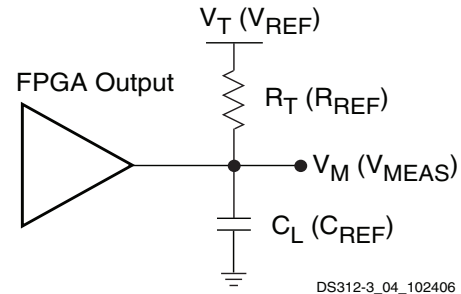
Timing Measurement Methodology

When measuring timing parameters at the programmable I/Os, different signal standards call for different test conditions. Table 27 lists the conditions to use for each standard.

The method for measuring Input timing is as follows: A signal that swings between a Low logic level of V_L and a High logic level of V_H is applied to the Input under test. Some standards also require the application of a bias voltage to the V_{REF} pins of a given bank to properly set the input-switching threshold. The measurement point of the Input signal (V_M) is commonly located halfway between V_L and V_H .

The Output test setup is shown in Figure 9. A termination voltage V_T is applied to the termination resistor R_T , the other end of which is connected to the Output. For each standard, R_T and V_T generally take on the standard values recommended for minimizing signal reflections. If the standard does not ordinarily use terminations (for example,

LVC MOS, LVTTTL), then R_T is set to $1M\Omega$ to indicate an open connection, and V_T is set to zero. The same measurement point (V_M) that was used at the Input is also used at the Output.



Notes:

1. The names shown in parentheses are used in the IBIS file.

Figure 9: Output Test Setup

Table 27: Test Methods for Timing Measurement at I/Os

Signal Standard (IOSTANDARD)		Inputs			Outputs		Inputs and Outputs
		V_{REF} (V)	V_L (V)	V_H (V)	R_T (Ω)	V_T (V)	V_M (V)
Single-Ended							
LVTTTL		-	0	3.3	1M	0	1.4
LVC MOS33		-	0	3.3	1M	0	1.65
LVC MOS25		-	0	2.5	1M	0	1.25
LVC MOS18		-	0	1.8	1M	0	0.9
LVC MOS15		-	0	1.5	1M	0	0.75
LVC MOS12		-	0	1.2	1M	0	0.6
PCI33_3	Rising	-	Note 3	Note 3	25	0	0.94
	Falling				25	3.3	2.03
PCI66_3	Rising	-	Note 3	Note 3	25	0	0.94
	Falling				25	3.3	2.03
HSTL_I		0.75	$V_{REF} - 0.5$	$V_{REF} + 0.5$	50	0.75	V_{REF}
HSTL_III		0.9	$V_{REF} - 0.5$	$V_{REF} + 0.5$	50	1.5	V_{REF}
HSTL_I_18		0.9	$V_{REF} - 0.5$	$V_{REF} + 0.5$	50	0.9	V_{REF}
HSTL_II_18		0.9	$V_{REF} - 0.5$	$V_{REF} + 0.5$	25	0.9	V_{REF}
HSTL_III_18		1.1	$V_{REF} - 0.5$	$V_{REF} + 0.5$	50	1.8	V_{REF}
SSTL18_I		0.9	$V_{REF} - 0.5$	$V_{REF} + 0.5$	50	0.9	V_{REF}
SSTL18_II		0.9	$V_{REF} - 0.5$	$V_{REF} + 0.5$	25	0.9	V_{REF}
SSTL2_I		1.25	$V_{REF} - 0.75$	$V_{REF} + 0.75$	50	1.25	V_{REF}
SSTL2_II		1.25	$V_{REF} - 0.75$	$V_{REF} + 0.75$	25	1.25	V_{REF}
SSTL3_I		1.5	$V_{REF} - 0.75$	$V_{REF} + 0.75$	50	1.5	V_{REF}
SSTL3_II		1.5	$V_{REF} - 0.75$	$V_{REF} + 0.75$	25	1.5	V_{REF}

Configurable Logic Block (CLB) Timing

Table 30: CLB (SLICEM) Timing

Symbol	Description	Speed Grade				Units
		-5		-4		
		Min	Max	Min	Max	
Clock-to-Output Times						
T _{CKO}	When reading from the FFX (FFY) Flip-Flop, the time from the active transition at the CLK input to data appearing at the XQ (YQ) output	–	0.60	–	0.68	ns
Setup Times						
T _{AS}	Time from the setup of data at the F or G input to the active transition at the CLK input of the CLB	0.18	–	0.36	–	ns
T _{DICK}	Time from the setup of data at the BX or BY input to the active transition at the CLK input of the CLB	1.58	–	1.88	–	ns
Hold Times						
T _{AH}	Time from the active transition at the CLK input to the point where data is last held at the F or G input	0	–	0	–	ns
T _{CKDI}	Time from the active transition at the CLK input to the point where data is last held at the BX or BY input	0	–	0	–	ns
Clock Timing						
T _{CH}	The High pulse width of the CLB's CLK signal	0.63	–	0.75	–	ns
T _{CL}	The Low pulse width of the CLK signal	0.63	–	0.75	–	ns
F _{TOG}	Toggle frequency (for export control)	0	770	0	667	MHz
Propagation Times						
T _{ILO}	The time it takes for data to travel from the CLB's F (G) input to the X (Y) output	–	0.62	–	0.71	ns
Set/Reset Pulse Width						
T _{RPW_CLB}	The minimum allowable pulse width, High or Low, to the CLB's SR input	1.33	–	1.61	–	ns

Notes:

1. The numbers in this table are based on the operating conditions set forth in [Table 8](#).

Clock Buffer/Multiplexer Switching Characteristics

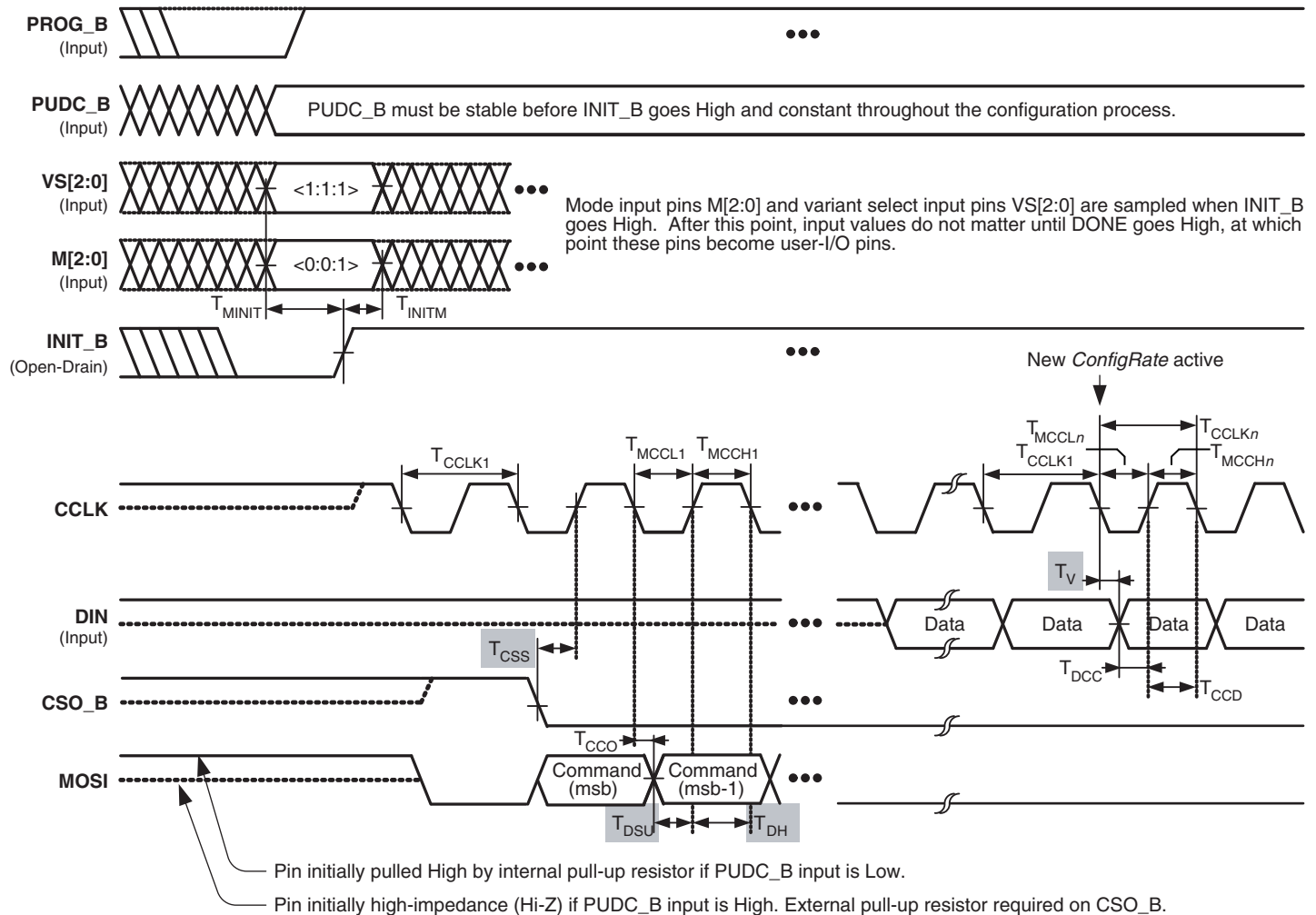
Table 33: Clock Distribution Switching Characteristics

Description	Symbol	Minimum	Maximum		Units
			Speed Grade		
			-5	-4	
Global clock buffer (BUFG, BUFGMUX, BUFGCE) I input to O-output delay	T _{GIO}	–	0.22	0.23	ns
Global clock multiplexer (BUFGMUX) select S-input setup to I0 and I1 inputs. Same as BUFGCE enable CE-input	T _{GSI}	–	0.56	0.63	ns
Frequency of signals distributed on global buffers (all sides)	F _{BUFG}	0	350	334	MHz

Notes:

1. The numbers in this table are based on the operating conditions set forth in [Table 8](#).

Serial Peripheral Interface (SPI) Configuration Timing



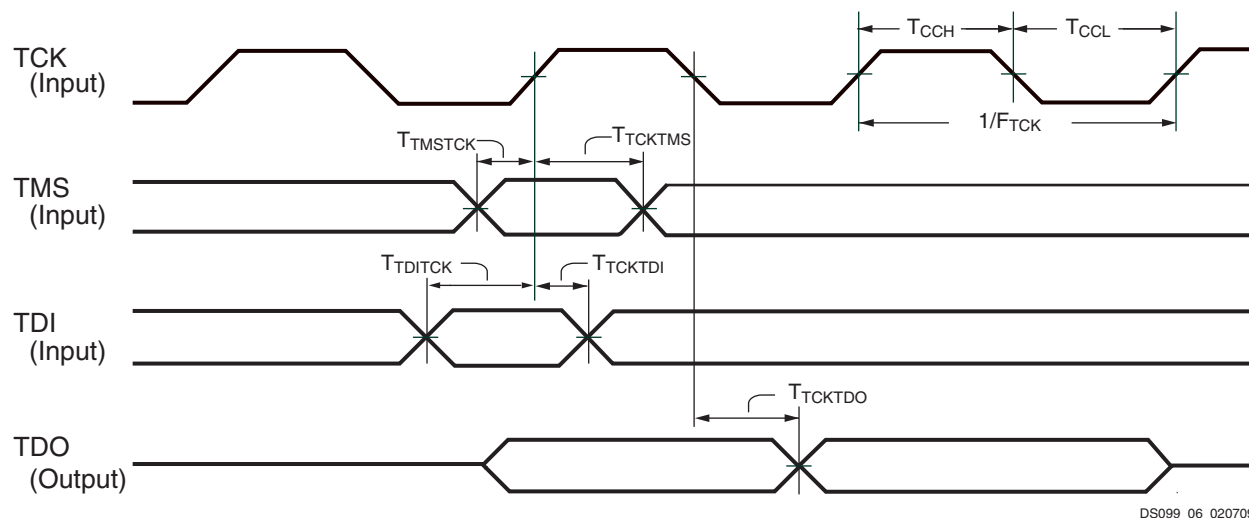
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Figure 14: Waveforms for Serial Peripheral Interface (SPI) Configuration

Table 52: Timing for Serial Peripheral Interface (SPI) Configuration Mode

Symbol	Description	Minimum	Maximum	Units
T_{CCLK1}	Initial CCLK clock period	See Table 46		
T_{CCLKn}	CCLK clock period after FPGA loads ConfigRate bitstream option setting	See Table 46		
T_{MINIT}	Setup time on VS[2:0] variant-select pins and M[2:0] mode pins before the rising edge of INIT_B	50	—	ns
T_{INITM}	Hold time on VS[2:0] variant-select pins and M[2:0] mode pins after the rising edge of INIT_B	0	—	ns
T_{CCO}	MOSI output valid delay after CCLK falling clock edge	See Table 50		
T_{DCC}	Setup time on the DIN data input before CCLK rising clock edge	See Table 50		
T_{CCD}	Hold time on the DIN data input after CCLK rising clock edge	See Table 50		

IEEE 1149.1/1532 JTAG Test Access Port Timing



DS099_06_020709

Figure 16: JTAG Waveforms

Table 56: Timing for the JTAG Test Access Port

Symbol	Description		All Speed Grades		Units
			Min	Max	
Clock-to-Output Times					
T _{TCKTDO}	The time from the falling transition on the TCK pin to data appearing at the TDO pin		1.0	11.0	ns
Setup Times					
T _{TDITCK}	The time from the setup of data at the TDI pin to the rising transition at the TCK pin	All devices and functions except those shown below	7.0	—	ns
		Boundary scan commands (INTEST, EXTEST, SAMPLE) on XC3S700A and XC3S1400A FPGAs	11.0		
T _{TMSTCK}	The time from the setup of a logic level at the TMS pin to the rising transition at the TCK pin		7.0	—	ns
Hold Times					
T _{TCKTDI}	The time from the rising transition at the TCK pin to the point when data is last held at the TDI pin	All functions except those shown below	0	—	ns
		Configuration commands (CFG_IN, ISC_PROGRAM)	2.0		
T _{TCKTMS}	The time from the rising transition at the TCK pin to the point when a logic level is last held at the TMS pin		0	—	ns
Clock Timing					
T _{CCH}	The High pulse width at the TCK pin	All functions except ISC_DNA command	5	—	ns
T _{CCL}	The Low pulse width at the TCK pin		5	—	ns
T _{CCHDNA}	The High pulse width at the TCK pin	During ISC_DNA command	10	10,000	ns
T _{CCLDNA}	The Low pulse width at the TCK pin		10	10,000	ns
F _{TCK}	Frequency of the TCK signal	All operations on XC3S50A, XC3S200A, and XC3S400A FPGAs and for BYPASS or HIGHZ instructions on all FPGAs	0	33	MHz
		All operations on XC3S700A and XC3S1400A FPGAs, except for BYPASS or HIGHZ instructions		20	

Notes:

- The numbers in this table are based on the operating conditions set forth in [Table 8](#).
- For details on JTAG see Chapter 9 “JTAG Configuration Mode and Boundary-Scan” in [UG332 Spartan-3 Generation Configuration User Guide](#).

Table 57: Types of Pins on Spartan-3A FPGAs(Continued)

Type / Color Code	Description	Pin Name(s) in Type
PWR MGMT	Control and status pins for the power-saving Suspend mode. SUSPEND is a dedicated pin and is powered by V _{CCAUX} . AWAKE is a dual-purpose pin. Unless Suspend mode is enabled in the application, AWAKE is available as a user-I/O pin.	SUSPEND, AWAKE
JTAG	Dedicated JTAG pin - 4 per device. Not available as a user-I/O pin. Every package has four dedicated JTAG pins. These pins are powered by V _{CCAUX} .	TDI, TMS, TCK, TDO
GND	Dedicated ground pin. The number of GND pins depends on the package used. All must be connected.	GND
VCCAUX	Dedicated auxiliary power supply pin. The number of VCCAUX pins depends on the package used. All must be connected. V _{CCAUX} can be either 2.5V or 3.3V. Set on board and using CONFIG VCCAUX constraint.	VCCAUX
VCCINT	Dedicated internal core logic power supply pin. The number of VCCINT pins depends on the package used. All must be connected to +1.2V.	VCCINT
VCCO	Along with all the other VCCO pins in the same bank, this pin supplies power to the output buffers within the I/O bank and sets the input threshold voltage for some I/O standards. All must be connected.	VCCO_#
N.C.	This package pin is not connected in this specific device/package combination but may be connected in larger devices in the same package.	N.C.

Notes:

1. # = I/O bank number, an integer between 0 and 3.

Package Pins by Type

Each package has three separate voltage supply inputs—VCCINT, VCCAUX, and VCCO—and a common ground return, GND. The numbers of pins dedicated to these functions vary by package, as shown in [Table 58](#).

Table 58: Power and Ground Supply Pins by Package

Package	VCCINT	VCCAUX	VCCO	GND
VQ100	4	3	6	13
TQ144	4	4	8	13
FT256 (50A/200A/400A)	6	4	16	28
FT256 (700A/1400A)	15	10	13	50
FG320	6	8	16	32
FG400	9	8	22	43
FG484	15	10	24	53
FG676	23	14	36	77

A majority of package pins are user-defined I/O or input pins. However, the numbers and characteristics of these I/O depend on the device type and the package in which it is available, as shown in [Table 59](#). The table shows the maximum number of single-ended I/O pins available, assuming that all I/O-, INPUT-, DUAL-, VREF-, and CLK-type pins are used as general-purpose I/O. AWAKE is counted here as a dual-purpose I/O pin. Likewise, the table shows the maximum number of differential pin-pairs available on the package. Finally, the table shows how the total maximum user-I/Os are distributed by pin type, including the number of unconnected—N.C.—pins on the device.

Not all I/O standards are supported on all I/O banks. The left and right banks (I/O banks 1 and 3) support higher output drive current than the top and bottom banks (I/O banks 0 and 2). Similarly, true differential output standards, such as LVDS, RSFS, PPDS, miniLVDS, and TMDS, are only supported in the top or bottom banks (I/O banks 0 and 2). Inputs are unrestricted. For more details, see the chapter “Using I/O Resources” in [UG331](#).

Table 59: Maximum User I/O by Package

Device	Package	Maximum User I/Os and Input-Only	Maximum Input-Only	Maximum Differential Pairs	All Possible I/Os by Type					
					I/O	INPUT	DUAL	VREF	CLK	N.C.
XC3S50A	VQ100	68	6	60	17	2	20	6	23	0
XC3S200A		68	6	60	17	2	20	6	23	0
XC3S50A	TQ144	108	7	50	42	2	26	8	30	0
XC3S50A	FT256	144	32	64	53	20	26	15	30	51
XC3S200A		195	35	90	69	21	52	21	32	0
XC3S400A		195	35	90	69	21	52	21	32	0
XC3S700A		161	13	60	59	2	52	18	30	0
XC3S1400A		161	13	60	59	2	52	18	30	0
XC3S200A	FG320	248	56	112	101	40	52	23	32	3
XC3S400A		251	59	112	101	42	52	24	32	0
XC3S400A	FG400	311	63	142	155	46	52	26	32	0
XC3S700A		311	63	142	155	46	52	26	32	0
XC3S700A	FG484	372	84	165	194	61	52	33	32	3
XC3S1400A		375	87	165	195	62	52	34	32	0
XC3S1400A	FG676	502	94	227	313	67	52	38	32	17

Notes:

1. Some VREFs are on INPUT pins. See pinout tables for details.

Electronic versions of the package pinout tables and footprints are available for download from the Xilinx website. Using a spreadsheet program, the data can be sorted and reformatted according to any specific needs. Similarly, the ASCII-text file is easily parsed by most scripting programs.

http://www.xilinx.com/support/documentation/data_sheets/s3a_pin.zip

VQ100 Footprint (XC3S50A)

Note pin 1 indicator in top-left corner and logo orientation.

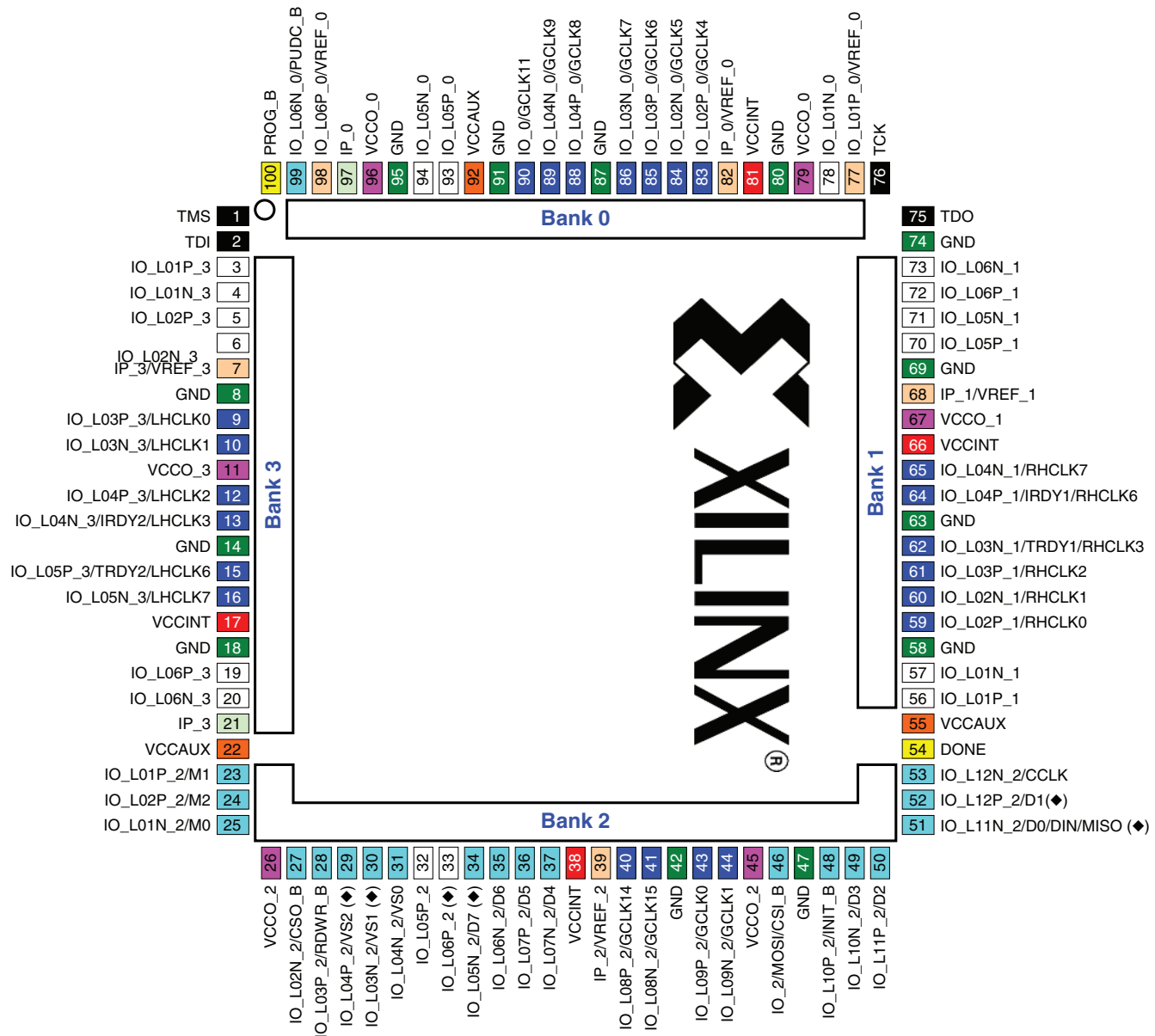


Figure 17: VQ100 Package Footprint - XC3S50A (Top View)

17	I/O: Unrestricted, general-purpose user I/O	20	DUAL: Configuration pins, then possible user I/O	6	VREF: User I/O or input voltage reference for bank
2	INPUT: Unrestricted, general-purpose input pin	23	CLK: User I/O, input, or global buffer input	6	VCCO: Output voltage supply for bank
2	CONFIG: Dedicated configuration pins	4	JTAG: Dedicated JTAG port pins	4	VCCINT: Internal core supply voltage (+1.2V)
0	N.C.: Not connected	13	GND: Ground	3	VCCAUX: Auxiliary supply voltage

Table 66: Spartan-3A TQ144 Pinout(Continued)

Bank	Pin Name	Pin	Type
2	IO_L05P_2	P46	I/O
2	IO_L06N_2/D6	P49	DUAL
2	IO_L06P_2	P47	I/O
2	IO_L07N_2/D4	P51	DUAL
2	IO_L07P_2/D5	P50	DUAL
2	IO_L08N_2/GCLK15	P55	GCLK
2	IO_L08P_2/GCLK14	P54	GCLK
2	IO_L09N_2/GCLK1	P59	GCLK
2	IO_L09P_2/GCLK0	P57	GCLK
2	IO_L10N_2/GCLK3	P60	GCLK
2	IO_L10P_2/GCLK2	P58	GCLK
2	IO_L11N_2/DOOUT	P64	DUAL
2	IO_L11P_2/AWAKE	P63	PWR MGMT
2	IO_L12N_2/D3	P68	DUAL
2	IO_L12P_2/INIT_B	P67	DUAL
2	IO_L13N_2/D0/DIN/MISO	P71	DUAL
2	IO_L13P_2/D2	P69	DUAL
2	IO_L14N_2/CCLK	P72	DUAL
2	IO_L14P_2/D1	P70	DUAL
2	IP_2/VREF_2	P53	VREF
2	VCCO_2	P40	VCCO
2	VCCO_2	P61	VCCO
3	IO_L01N_3	P6	I/O
3	IO_L01P_3	P4	I/O
3	IO_L02N_3	P5	I/O
3	IO_L02P_3	P3	I/O
3	IO_L03N_3	P8	I/O
3	IO_L03P_3	P7	I/O
3	IO_L04N_3/VREF_3	P11	VREF
3	IO_L04P_3	P10	I/O
3	IO_L05N_3/LHCLK1	P13	LHCLK
3	IO_L05P_3/LHCLK0	P12	LHCLK
3	IO_L06N_3/IRDY2/LHCLK3	P16	LHCLK
3	IO_L06P_3/LHCLK2	P15	LHCLK
3	IO_L07N_3/LHCLK5	P20	LHCLK
3	IO_L07P_3/LHCLK4	P18	LHCLK
3	IO_L08N_3/LHCLK7	P21	LHCLK
3	IO_L08P_3/TRDY2/LHCLK6	P19	LHCLK
3	IO_L09N_3	P25	I/O
3	IO_L09P_3	P24	I/O
3	IO_L10N_3	P29	I/O

Table 66: Spartan-3A TQ144 Pinout(Continued)

Bank	Pin Name	Pin	Type
3	IO_L10P_3	P27	I/O
3	IO_L11N_3	P30	I/O
3	IO_L11P_3	P28	I/O
3	IO_L12N_3	P32	I/O
3	IO_L12P_3	P31	I/O
3	IP_L13N_3/VREF_3	P35	VREF
3	IP_L13P_3	P33	INPUT
3	VCCO_3	P14	VCCO
3	VCCO_3	P23	VCCO
GND	GND	P9	GND
GND	GND	P17	GND
GND	GND	P26	GND
GND	GND	P34	GND
GND	GND	P56	GND
GND	GND	P65	GND
GND	GND	P81	GND
GND	GND	P89	GND
GND	GND	P100	GND
GND	GND	P106	GND
GND	GND	P118	GND
GND	GND	P128	GND
GND	GND	P137	GND
VCCAUX	SUSPEND	P74	PWR MGMT
VCCAUX	DONE	P73	CONFIG
VCCAUX	PROG_B	P144	CONFIG
VCCAUX	TCK	P109	JTAG
VCCAUX	TDI	P2	JTAG
VCCAUX	TDO	P107	JTAG
VCCAUX	TMS	P1	JTAG
VCCAUX	VCCAUX	P36	VCCAUX
VCCAUX	VCCAUX	P66	VCCAUX
VCCAUX	VCCAUX	P108	VCCAUX
VCCAUX	VCCAUX	P133	VCCAUX
VCCINT	VCCINT	P22	VCCINT
VCCINT	VCCINT	P52	VCCINT
VCCINT	VCCINT	P94	VCCINT
VCCINT	VCCINT	P122	VCCINT

Table 68: Spartan-3A FT256 Pinout (XC3S50A, XC3S200A, XC3S400) (Continued)

Bank	XC3S50A	XC3S200A XC3S400A	FT256 Ball	Type
3	IO_L14N_3/ LHCLK5	IO_L14N_3/ LHCLK5	J1	LHCLK
3	IO_L14P_3/ LHCLK4	IO_L14P_3/ LHCLK4	J2	LHCLK
3	IO_L15N_3/ LHCLK7	IO_L15N_3/ LHCLK7	K1	LHCLK
3	IO_L15P_3/ TRDY2/LHCLK6	IO_L15P_3/ TRDY2/LHCLK6	K3	LHCLK
3	N.C. (◆)	IO_L16N_3	L2	I/O
3	N.C. (◆)	IO_L16P_3/ VREF_3	L1	VREF
3	N.C. (◆)	IO_L17N_3	J6	I/O
3	N.C. (◆)	IO_L17P_3	J4	I/O
3	N.C. (◆)	IO_L18N_3	L3	I/O
3	N.C. (◆)	IO_L18P_3	K4	I/O
3	N.C. (◆)	IO_L19N_3	L4	I/O
3	N.C. (◆)	IO_L19P_3	M3	I/O
3	IO_L20N_3	IO_L20N_3	N1	I/O
3	IO_L20P_3	IO_L20P_3	M1	I/O
3	IO_L22N_3	IO_L22N_3	P1	I/O
3	IO_L22P_3	IO_L22P_3	N2	I/O
3	IO_L23N_3	IO_L23N_3	P2	I/O
3	IO_L23P_3	IO_L23P_3	R1	I/O
3	IO_L24N_3	IO_L24N_3	M4	I/O
3	IO_L24P_3	IO_L24P_3	N3	I/O
3	IP_L04N_3/ VREF_3	IP_L04N_3/ VREF_3	F4	VREF
3	IP_L04P_3	IP_L04P_3	E4	INPUT
3	N.C. (◆)	IP_L06N_3/ VREF_3	G5	VREF
3	N.C. (◆)	IP_L06P_3	G6	INPUT
3	IP_L13N_3	IP_L13N_3	J7	INPUT
3	IP_L13P_3	IP_L13P_3	H7	INPUT
3	IP_L21N_3	IP_L21N_3	K6	INPUT
3	IP_L21P_3	IP_L21P_3	K5	INPUT
3	IP_L25N_3/ VREF_3	IP_L25N_3/ VREF_3	L6	VREF
3	IP_L25P_3	IP_L25P_3	L5	INPUT
3	VCCO_3	VCCO_3	D2	VCCO
3	VCCO_3	VCCO_3	H2	VCCO
3	VCCO_3	VCCO_3	J5	VCCO
3	VCCO_3	VCCO_3	M2	VCCO
GND	GND	GND	A1	GND
GND	GND	GND	A16	GND
GND	GND	GND	B7	GND

Table 68: Spartan-3A FT256 Pinout (XC3S50A, XC3S200A, XC3S400) (Continued)

Bank	XC3S50A	XC3S200A XC3S400A	FT256 Ball	Type
GND	GND	GND	B11	GND
GND	GND	GND	C3	GND
GND	GND	GND	C14	GND
GND	GND	GND	E5	GND
GND	GND	GND	E12	GND
GND	GND	GND	F2	GND
GND	GND	GND	F6	GND
GND	GND	GND	G8	GND
GND	GND	GND	G10	GND
GND	GND	GND	G15	GND
GND	GND	GND	H9	GND
GND	GND	GND	J8	GND
GND	GND	GND	K2	GND
GND	GND	GND	K7	GND
GND	GND	GND	K9	GND
GND	GND	GND	L11	GND
GND	GND	GND	L15	GND
GND	GND	GND	M5	GND
GND	GND	GND	M12	GND
GND	GND	GND	P3	GND
GND	GND	GND	P14	GND
GND	GND	GND	R6	GND
GND	GND	GND	R10	GND
GND	GND	GND	T1	GND
GND	GND	GND	T16	GND
VCCAUX	SUSPEND	SUSPEND	R16	PWR MGMT
VCCAUX	DONE	DONE	T15	CONFIG
VCCAUX	PROG_B	PROG_B	A2	CONFIG
VCCAUX	TCK	TCK	A15	JTAG
VCCAUX	TDI	TDI	B1	JTAG
VCCAUX	TDO	TDO	B16	JTAG
VCCAUX	TMS	TMS	B2	JTAG
VCCAUX	VCCAUX	VCCAUX	E11	VCCAUX
VCCAUX	VCCAUX	VCCAUX	F5	VCCAUX
VCCAUX	VCCAUX	VCCAUX	L12	VCCAUX
VCCAUX	VCCAUX	VCCAUX	M6	VCCAUX
VCCINT	VCCINT	VCCINT	G7	VCCINT
VCCINT	VCCINT	VCCINT	G9	VCCINT
VCCINT	VCCINT	VCCINT	H8	VCCINT
VCCINT	VCCINT	VCCINT	J9	VCCINT

FT256 Footprint (XC3S700A, XC3S1400A)

Bank 0																
	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16
A	GND	PROG_B	I/O L19P_0	I/O L18P_0	I/O L17P_0	I/O L15P_0	I/O L13P_0	I/O L12P_0 GCLK10	I/O L10N_0 GCLK7	I/O L08N_0	I/O L07N_0	I/O L05N_0	I/O L04N_0	I/O L04P_0	TCK	GND
B	TDI	TMS	I/O L19N_0	I/O L18N_0	VCCO_0	I/O L15N_0	GND	I/O L12N_0 GCLK11	VCCO_0	I/O L08P_0	GND	I/O L05P_0	VCCO_0	I/O L02N_0	I/O L02P_0 VREF_0	TDO
C	I/O L01N_3	I/O L01P_3	GND	I/O L20P_0 VREF_0	I/O L17N_0	I/O L16N_0	I/O L13N_0	I/O L11P_0 GCLK8	I/O L10P_0 GCLK6	I/O L09P_0 GCLK4	I/O L07P_0	I/O L03P_0	I/O L01N_0	GND	I/O L24N_1 A25	I/O L24P_1 A24
D	I/O L03P_3	VCCO_3	I/O L02N_3	I/O L02P_3	I/O L20N_0 PUDC_B	VCCAUX	I/O L16P_0	I/O L11N_0 GCLK9	I/O L09N_0 GCLK5	I/O L06N_0 VREF_0	I/O L06P_0	I/O L03N_0	I/O L01P_0	I/O L23N_1 A23	I/O L22N_1 A21	I/O L22P_1 A20
E	I/O L03N_3	I/O L05N_3	I/O L05P_3	I/O L04P_3	GND	INPUT	I/O L14N_0 VREF_0	VCCO_0	I/O L14P_0	GND	VCCAUX	GND	I/O L23P_1 A22	I/O L20P_1 A18	VCCO_1	I/O L18P_1 A14
F	I/O L08P_3	GND	I/O L07P_3	I/O L04N_3	VCCAUX	GND	GND	GND	GND	VCCINT	GND	VCCAUX	I/O L20N_1 A19	I/O L19N_1 A17	I/O L18N_1 A15	I/O L16N_1 A11
G	I/O L08N_3 VREF_3	I/O L11P_3 LHCLK0	I/O L07N_3	INPUT VREF_3	GND	GND	VCCINT	GND	VCCINT	GND	VCCINT	GND	I/O L19P_1 A16	I/O L17N_1 A13	GND	I/O L16P_1 A10
H	I/O L11N_3 LHCLK1	VCCO_3	I/O L12P_3 LHCLK2	VCCAUX	GND	VCCINT	GND	VCCINT	GND	VCCINT	GND	INPUT VREF_1	I/O L17P_1 A12	VCCAUX	I/O L15P_1 IRDY1 RHCLK6	I/O L15N_1 RHCLK7
J	I/O L14N_3 LHCLK5	I/O L14P_3 LHCLK4	I/O L12N_3 IRDY2 LHCLK3	INPUT	INPUT VREF_3	GND	VCCINT	GND	VCCINT	GND	VCCINT	I/O L10P_1 A8	I/O L10N_1 A9	INPUT VREF_1	VCCO_1	I/O L12N_1 TRDY1 RHCLK3
K	I/O L15N_3 LHCLK7	GND	I/O L15P_3 TRDY2 LHCLK6	I/O L18P_3	GND	VCCINT	GND	VCCINT	GND	VCCINT	GND	GND	I/O L06N_1 A3	I/O L11N_1 RHCLK1	I/O L11P_1 RHCLK0	I/O L12P_1 RHCLK2
L	I/O L16P_3 VREF_3	I/O L16N_3	I/O L18N_3	I/O L19N_3	VCCAUX	GND	VCCINT	GND	VCCINT	GND	GND	VCCAUX	I/O L06P_1 A2	I/O L08P_1 A6	GND	I/O L08N_1 A7
M	I/O L20P_3	VCCO_3	I/O L19P_3	I/O L24N_3	GND	VCCAUX	INPUT VREF_2	GND	INPUT VREF_2	VCCAUX	INPUT VREF_2	GND	INPUT VREF_1	INPUT VREF_1	I/O L07P_1 A4	I/O L07N_1 A5
N	I/O L20N_3	I/O L22P_3 VREF_3	I/O L24P_3	I/O L01P_2 M1	INPUT VREF_2	I/O L04P_2 VS1	GND	I/O L08N_2 D4	I/O L11P_2 GCLK0	GND	I/O L16N_2	I/O L19P_2	I/O L01P_1 HDC	I/O L01N_1 LDC2	VCCO_1	I/O L03N_1 A1
P	I/O L22N_3	I/O L23N_3	GND	I/O L01N_2 M0	I/O L04N_2 VS0	INPUT VREF_2	I/O L08P_2 D5	I/O L10P_2 GCLK14	I/O L11N_2 GCLK1	I/O L14N_2 MOSI CSI_B	I/O L16P_2	I/O L17N_2 D3	I/O L19N_2	GND	I/O L02N_1 LDC0	I/O L03P_1 A0
R	I/O L23P_3	I/O L02P_2 M2	I/O L03P_2 RDWR_B	VCCO_2	I/O L05N_2	GND	I/O L09P_2 GCLK12	VCCO_2	I/O L12P_2 GCLK2	GND	I/O L15N_2 DOUT	VCCO_2	I/O L18N_2 D1	I/O L20N_2 CCLK	I/O L02P_1 LDC1	SUSPEND
T	GND	I/O L02N_2 CSO_B	I/O L03N_2 VS2	I/O L05P_2	I/O L06P_2 D7	I/O L06N_2 D6	I/O L09N_2 GCLK13	I/O L10N_2 GCLK15	I/O L12N_2 GCLK3	I/O L14P_2	I/O L15P_2 AWAKE	I/O L17P_2 INIT_B	I/O L18P_2 D2	I/O L20P_2 DO/DIN MISO	DONE	GND
Bank 2																

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Figure 22: XC3S700A and XC3S1400A FT256 Package Footprint (Top View)

59	I/O: Unrestricted, general-purpose user I/O	51	DUAL: Configuration, then possible user I/O	18	VREF: User I/O or input voltage reference for bank	2	SUSPEND: Dedicated SUSPEND and dual-purpose AWAKE Power Management pins
2	INPUT: Unrestricted, general-purpose input pin	30	CLK: User I/O, input, or global buffer input	13	VCCO: Output voltage supply for bank		
2	CONFIG: Dedicated configuration pins	4	JTAG: Dedicated JTAG port pins	15	VCCINT: Internal core supply voltage (+1.2V)		
0	N.C.: Not connected	50	GND: Ground	10	VCCAUX: Auxiliary supply voltage		

FG320 Footprint

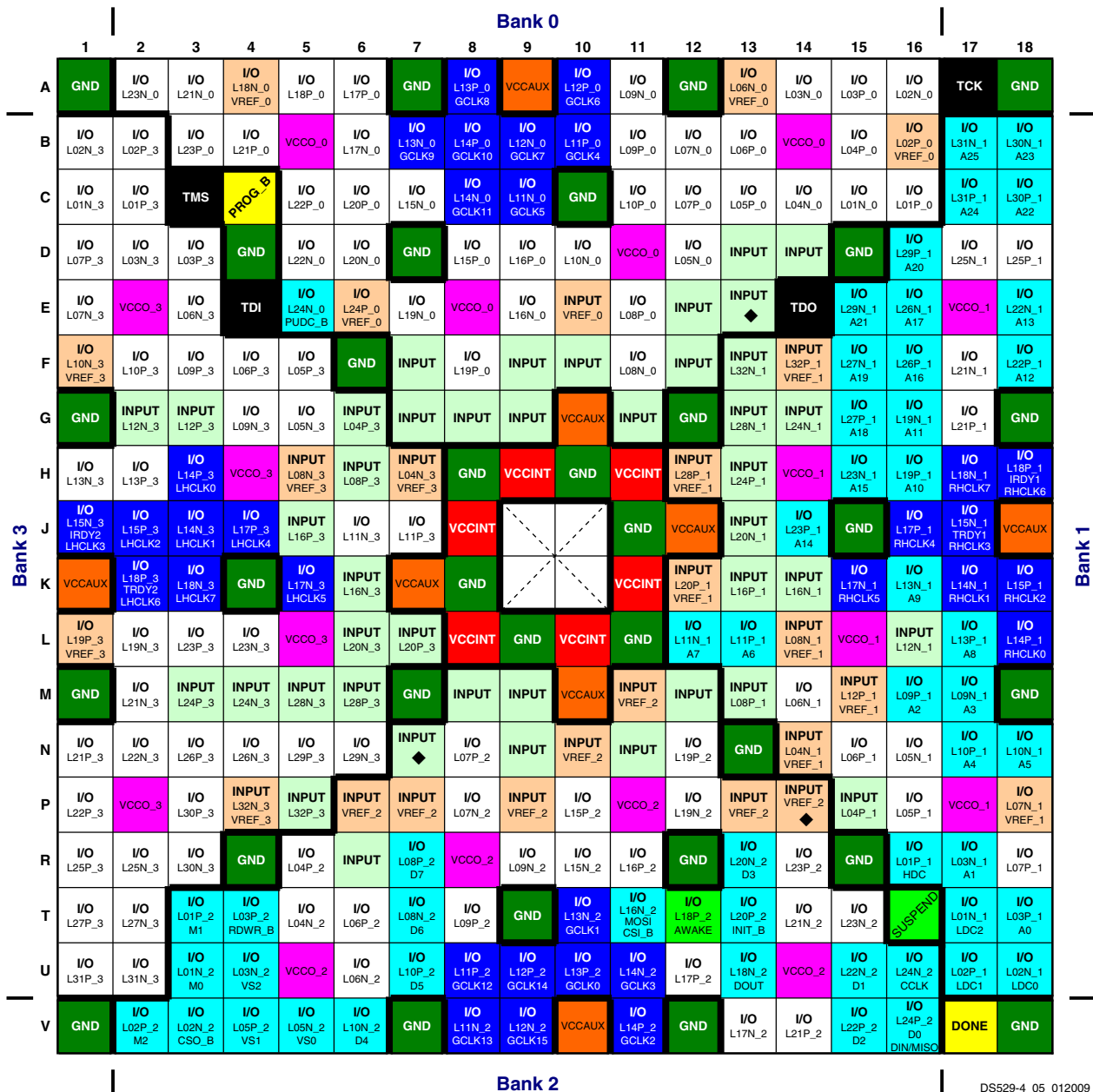


Figure 23: FG320 Package Footprint (Top View)

101	I/O: Unrestricted, general-purpose user I/O	51	DUAL: Configuration pins, then possible user-I/O	23 - 24	VREF: User I/O or input voltage reference for bank	2	SUSPEND: Dedicated SUSPEND and dual-purpose AWAKE Power Management pins
40 - 42	INPUT: Unrestricted, general-purpose input pin	32	CLK: User I/O, input, or global buffer input	16	VCCO: Output voltage supply for bank		
2	CONFIG: Dedicated configuration pins	4	JTAG: Dedicated JTAG port pins	6	VCCINT: Internal core supply voltage (+1.2V)		
3	N.C.: Not connected. Only the XC3S200A has these pins (◆).	32	GND: Ground	8	VCCAUX: Auxiliary supply voltage		

Table 81: Spartan-3A FG400 Pinout(Continued)

Bank	Pin Name	FG400 Ball	Type
3	IO_L34P_3	U1	I/O
3	IO_L36N_3	T4	I/O
3	IO_L36P_3	R5	I/O
3	IO_L37N_3	V2	I/O
3	IO_L37P_3	V1	I/O
3	IO_L38N_3	W2	I/O
3	IO_L38P_3	W1	I/O
3	IP_3	H7	INPUT
3	IP_L04N_3/VREF_3	G6	VREF
3	IP_L04P_3	G7	INPUT
3	IP_L11N_3/VREF_3	J7	VREF
3	IP_L11P_3	J8	INPUT
3	IP_L15N_3	K7	INPUT
3	IP_L15P_3	K8	INPUT
3	IP_L19N_3	K5	INPUT
3	IP_L19P_3	K6	INPUT
3	IP_L23N_3	L6	INPUT
3	IP_L23P_3	L7	INPUT
3	IP_L27N_3	M7	INPUT
3	IP_L27P_3	M8	INPUT
3	IP_L31N_3	N7	INPUT
3	IP_L31P_3	M6	INPUT
3	IP_L35N_3	N6	INPUT
3	IP_L35P_3	P5	INPUT
3	IP_L39N_3/VREF_3	P7	VREF
3	IP_L39P_3	P6	INPUT
3	VCCO_3	E2	VCCO
3	VCCO_3	H5	VCCO
3	VCCO_3	L2	VCCO
3	VCCO_3	N5	VCCO
3	VCCO_3	U2	VCCO
GND	GND	A1	GND
GND	GND	A11	GND
GND	GND	A20	GND
GND	GND	B6	GND
GND	GND	B14	GND
GND	GND	C3	GND
GND	GND	C18	GND
GND	GND	D9	GND
GND	GND	E5	GND

Table 81: Spartan-3A FG400 Pinout(Continued)

Bank	Pin Name	FG400 Ball	Type
GND	GND	E12	GND
GND	GND	F15	GND
GND	GND	G2	GND
GND	GND	G19	GND
GND	GND	H8	GND
GND	GND	H13	GND
GND	GND	J9	GND
GND	GND	J11	GND
GND	GND	K1	GND
GND	GND	K10	GND
GND	GND	K12	GND
GND	GND	K17	GND
GND	GND	L4	GND
GND	GND	L9	GND
GND	GND	L11	GND
GND	GND	L20	GND
GND	GND	M10	GND
GND	GND	M12	GND
GND	GND	N8	GND
GND	GND	N11	GND
GND	GND	N13	GND
GND	GND	P2	GND
GND	GND	P19	GND
GND	GND	R6	GND
GND	GND	R9	GND
GND	GND	T16	GND
GND	GND	U12	GND
GND	GND	V3	GND
GND	GND	V18	GND
GND	GND	W7	GND
GND	GND	W15	GND
GND	GND	Y1	GND
GND	GND	Y10	GND
GND	GND	Y20	GND
VCCAUX	SUSPEND	R15	PWR MGMT
VCCAUX	DONE	W19	CONFIG
VCCAUX	PROG_B	D5	CONFIG
VCCAUX	TCK	A19	JTAG
VCCAUX	TDI	F5	JTAG

Table 83: Spartan-3A FG484 Pinout(Continued)

Bank	Pin Name	FG484 Ball	Type
0	IO_L30P_0	E9	I/O
0	IO_L31N_0	B4	I/O
0	IO_L31P_0	A4	I/O
0	IO_L32N_0	D5	I/O
0	IO_L32P_0	C5	I/O
0	IO_L33N_0	B3	I/O
0	IO_L33P_0	A3	I/O
0	IO_L34N_0	F8	I/O
0	IO_L34P_0	E7	I/O
0	IO_L35N_0	E6	I/O
0	IO_L35P_0	F7	I/O
0	IO_L36N_0/PUDC_B	A2	DUAL
0	IO_L36P_0/VREF_0	B2	VREF
0	IP_0	E16	INPUT
0	IP_0	E8	INPUT
0	IP_0	F10	INPUT
0	IP_0	F12	INPUT
0	IP_0	F16	INPUT
0	IP_0	G10	INPUT
0	IP_0	G11	INPUT
0	IP_0	G12	INPUT
0	IP_0	G13	INPUT
0	IP_0	G14	INPUT
0	IP_0	G15	INPUT
0	IP_0	G16	INPUT
0	IP_0	G7	INPUT
0	IP_0	G9	INPUT
0	IP_0	H10	INPUT
0	IP_0	H13	INPUT
0	IP_0	H14	INPUT
0	IP_0/VREF_0	G8	VREF
0	IP_0/VREF_0	H12	VREF
0	IP_0/VREF_0	H9	VREF
0	VCCO_0	B10	VCCO
0	VCCO_0	B14	VCCO
0	VCCO_0	B18	VCCO
0	VCCO_0	B5	VCCO
0	VCCO_0	F14	VCCO
0	VCCO_0	F9	VCCO
1	IO_L01N_1/LDC2	Y21	DUAL

Table 83: Spartan-3A FG484 Pinout(Continued)

Bank	Pin Name	FG484 Ball	Type
1	IO_L01P_1/HDC	AA22	DUAL
1	IO_L02N_1/LDC0	W20	DUAL
1	IO_L02P_1/LDC1	W19	DUAL
1	IO_L03N_1/A1	T18	DUAL
1	IO_L03P_1/A0	T17	DUAL
1	IO_L05N_1	W21	I/O
1	IO_L05P_1	Y22	I/O
1	IO_L06N_1	V20	I/O
1	IO_L06P_1	V19	I/O
1	IO_L07N_1	V22	I/O
1	IO_L07P_1	W22	I/O
1	IO_L09N_1	U21	I/O
1	IO_L09P_1	U22	I/O
1	IO_L10N_1	U19	I/O
1	IO_L10P_1	U20	I/O
1	IO_L11N_1	T22	I/O
1	IO_L11P_1	T20	I/O
1	IO_L13N_1	T19	I/O
1	IO_L13P_1	R20	I/O
1	IO_L14N_1	R22	I/O
1	IO_L14P_1	R21	I/O
1	IO_L15N_1/VREF_1	P22	VREF
1	IO_L15P_1	P20	I/O
1	IO_L17N_1/A3	P18	DUAL
1	IO_L17P_1/A2	R19	DUAL
1	IO_L18N_1/A5	N21	DUAL
1	IO_L18P_1/A4	N22	DUAL
1	IO_L19N_1/A7	N19	DUAL
1	IO_L19P_1/A6	N20	DUAL
1	IO_L20N_1/A9	N17	DUAL
1	IO_L20P_1/A8	N18	DUAL
1	IO_L21N_1/RHCLK1	L22	RHCLK
1	IO_L21P_1/RHCLK0	M22	RHCLK
1	IO_L22N_1/TRDY1/RHCLK3	L20	RHCLK
1	IO_L22P_1/RHCLK2	L21	RHCLK
1	IO_L24N_1/RHCLK5	M20	RHCLK
1	IO_L24P_1/RHCLK4	M18	RHCLK
1	IO_L25N_1/RHCLK7	K19	RHCLK
1	IO_L25P_1/IRDY1/RHCLK6	K20	RHCLK
1	IO_L26N_1/A11	J22	DUAL

FG484 Footprint

Left Half of FG484 Package (Top View)

195 I/O: Unrestricted, general-purpose user I/O

60-62 INPUT: Unrestricted, general-purpose input pin

51 DUAL: Configuration pins, then possible user I/O

33-34 VREF: User I/O or input voltage reference for bank

32 CLK: User I/O, input, or clock buffer input

2 SUSPEND: Dedicated SUSPEND and dual-purpose AWAKE Power Management pins

2 CONFIG: Dedicated configuration pins

4 JTAG: Dedicated JTAG port pins

53 GND: Ground

24 VCCO: Output voltage supply for bank

15 VCCINT: Internal core supply voltage (+1.2V)

10 VCCAUX: Auxiliary supply voltage

3 N.C.: Not connected (XC3S700A only)

		Bank 0										
		1	2	3	4	5	6	7	8	9	10	11
Bank 3	A	GND	I/O L36N_0 PUDC_B	I/O L33P_0	I/O L31P_0	I/O L28N_0	I/O L26N_0	I/O L26P_0	I/O L22N_0	I/O L22P_0	I/O L21P_0	I/O L18N_0 GCLK7
	B	I/O L02P_3	I/O L36P_0 VREF_0	I/O L33N_0	I/O L31N_0	VCCO_0	I/O L28P_0	GND	I/O L25P_0	I/O L24P_0	VCCO_0	I/O L19P_0 GCLK8
	C	I/O L01P_3	I/O L02N_3	GND	PROG_B	I/O L32P_0	I/O L29P_0	I/O L27N_0	I/O L25N_0	I/O L24N_0 VREF_0	I/O L21N_0	I/O L19N_0 GCLK9
	D	I/O L06P_3	I/O L01N_3	I/O L03P_3	TMS	I/O L32N_0	I/O L29N_0	I/O L27P_0	I/O L30N_0	GND	I/O L23P_0	I/O L20P_0 GCLK10
	E	I/O L06N_3	VCCO_3	I/O L07N_3	I/O L03N_3	VCCAUX	I/O L35N_0	I/O L34P_0	INPUT	I/O L30P_0	I/O L23N_0	I/O L20N_0 GCLK11
	F	I/O L12N_3	I/O L12P_3	I/O L08P_3	I/O L07P_3	TDI	GND	I/O L35P_0	I/O L34N_0	VCCO_0	INPUT	GND
	G	I/O L13N_3	GND	I/O L13P_3	I/O L08N_3	I/O L05N_3	I/O L05P_3	INPUT	INPUT VREF_0	INPUT	INPUT	INPUT
	H	I/O L16N_3	I/O L16P_3	I/O L14N_3	I/O L14P_3	I/O L09P_3	I/O L09N_3	INPUT L04N_3 VREF_3	INPUT L04P_3	INPUT VREF_0	INPUT	VCCAUX
	J	I/O L17N_3 VREF_3	VCCO_3	I/O L17P_3	GND	I/O L10N_3	VCCO_3	INPUT L11P_3	INPUT VREF_3	GND	VCCINT	GND
	K	I/O L22P_3 LHCLK2	I/O L20N_3	I/O L20P_3	I/O L18N_3	I/O L18P_3	I/O L10P_3	INPUT L15P_3	INPUT L11N_3	VCCINT	GND	VCCINT
	L	I/O L22N_3 IRDY2 LHCLK3	GND	I/O L21N_3 LHCLK1	VCCAUX	I/O L21P_3 LHCLK0	GND	INPUT L19P_3	INPUT L15N_3 VREF_3	GND	VCCINT	GND
	M	I/O L24P_3 LHCLK4	I/O L24N_3 LHCLK5	I/O L25P_3 TRDY2 LHCLK6	I/O L25N_3 LHCLK7	I/O L30P_3	INPUT L23N_3	INPUT L23P_3	INPUT L19N_3	VCCINT	GND	VCCINT
	N	I/O L26P_3 VREF_3	VCCO_3	I/O L26N_3	I/O L30N_3	INPUT L31N_3	INPUT L31P_3	INPUT L35P_3	INPUT L27P_3	INPUT L27N_3	VCCINT	GND
	P	I/O L28P_3	I/O L28N_3	I/O L29P_3	GND	I/O L29N_3	VCCO_3	INPUT L39P_3	INPUT L35N_3	GND	GND	VCCAUX
	R	I/O L32P_3	I/O L32N_3	I/O L33P_3	I/O L33N_3	I/O L34P_3	INPUT VREF_3	INPUT L46P_3	INPUT L39N_3	INPUT	INPUT	INPUT
	T	I/O L36P_3 VREF_3	GND	I/O L36N_3	I/O L34N_3	I/O L40P_3	INPUT L46N_3 VREF_3	INPUT VREF_2	INPUT VREF_2	INPUT	INPUT VREF_2	INPUT VREF_2
	U	I/O L37P_3	I/O L37N_3	I/O L41P_3	I/O L41N_3	I/O L40N_3	GND	INPUT	INPUT	VCCO_2	INPUT	I/O L17P_2 GCLK12
	V	I/O L38P_3	VCCO_3	I/O L38N_3	I/O L43P_3	VCCAUX	I/O L01P_2 M1	INPUT	INPUT VREF_2	I/O L09P_2 RDWR_B	I/O L13P_2	I/O L17N_2 GCLK13
	W	I/O L42P_3	I/O L42N_3	I/O L43N_3	I/O L02P_2 M2	I/O L01N_2 M0	I/O L05P_2	I/O L07P_2	I/O L11P_2 VS1	I/O L09N_2 VS2	GND	VCCAUX
	Y	I/O L44P_3	I/O L44N_3	GND	I/O L02N_2 CSO_B	I/O L05N_2	I/O L07N_2	I/O L10P_2	I/O L11N_2 VS0	I/O L14P_2 D7	I/O L13N_2	I/O L16P_2 D5
	A	I/O L45P_3	I/O L45N_3	I/O L03N_2	I/O L04N_2	VCCO_2	I/O L08P_2	GND	I/O L12P_2	VCCO_2	I/O L15P_2	GND
	B	GND	I/O L03P_2	I/O L04P_2	I/O L06P_2	I/O L06N_2	I/O L08N_2	I/O L10N_2	I/O L12N_2	I/O L14N_2 D6	I/O L15N_2	I/O L16N_2 D4
		Bank 2										

Figure 25: FG484 Package Footprint (Top View)

DS529-4 01 101106

FG676: 676-ball Fine-pitch Ball Grid Array

The 676-ball fine-pitch ball grid array, FG676, supports the XC3S1400A FPGA.

Table 87 lists all the FG676 package pins. They are sorted by bank number and then by pin name. Pairs of pins that form a differential I/O pair appear together in the table. The table also shows the pin number for each pin and the pin type, as defined earlier.

The XC3S1400A has 17 unconnected balls, indicated as N.C. (No Connection) in Table 87 and with the black diamond character (◆) in Table 87 and Figure 27.

An electronic version of this package pinout table and footprint diagram is available for download from the Xilinx website at:

www.xilinx.com/support/documentation/data_sheets/s3a_pin.zip

Pinout Table

Table 87: Spartan-3A FG676 Pinout

Bank	Pin Name	FG676 Ball	Type
0	IO_L01N_0	F20	I/O
0	IO_L01P_0	G20	I/O
0	IO_L02N_0	F19	I/O
0	IO_L02P_0/VREF_0	G19	VREF
0	IO_L05N_0	C22	I/O
0	IO_L05P_0	D22	I/O
0	IO_L06N_0	C23	I/O
0	IO_L06P_0	D23	I/O
0	IO_L07N_0	A22	I/O
0	IO_L07P_0	B23	I/O
0	IO_L08N_0	G17	I/O
0	IO_L08P_0	H17	I/O
0	IO_L09N_0	B21	I/O
0	IO_L09P_0	C21	I/O
0	IO_L10N_0	D21	I/O
0	IO_L10P_0	E21	I/O
0	IO_L11N_0	C20	I/O
0	IO_L11P_0	D20	I/O
0	IO_L12N_0	K16	I/O
0	IO_L12P_0	J16	I/O
0	IO_L13N_0	E17	I/O
0	IO_L13P_0	F17	I/O
0	IO_L14N_0	A20	I/O
0	IO_L14P_0/VREF_0	B20	VREF

Table 87: Spartan-3A FG676 Pinout(Continued)

Bank	Pin Name	FG676 Ball	Type
0	IO_L15N_0	A19	I/O
0	IO_L15P_0	B19	I/O
0	IO_L16N_0	H15	I/O
0	IO_L16P_0	G15	I/O
0	IO_L17N_0	C18	I/O
0	IO_L17P_0	D18	I/O
0	IO_L18N_0	A18	I/O
0	IO_L18P_0	B18	I/O
0	IO_L19N_0	B17	I/O
0	IO_L19P_0	C17	I/O
0	IO_L20N_0/VREF_0	E15	VREF
0	IO_L20P_0	F15	I/O
0	IO_L21N_0	C16	I/O
0	IO_L21P_0	D17	I/O
0	IO_L22N_0	C15	I/O
0	IO_L22P_0	D16	I/O
0	IO_L23N_0	A15	I/O
0	IO_L23P_0	B15	I/O
0	IO_L24N_0	F14	I/O
0	IO_L24P_0	E14	I/O
0	IO_L25N_0/GCLK5	J14	GCLK
0	IO_L25P_0/GCLK4	K14	GCLK
0	IO_L26N_0/GCLK7	A14	GCLK
0	IO_L26P_0/GCLK6	B14	GCLK
0	IO_L27N_0/GCLK9	G13	GCLK
0	IO_L27P_0/GCLK8	F13	GCLK
0	IO_L28N_0/GCLK11	C13	GCLK
0	IO_L28P_0/GCLK10	B13	GCLK
0	IO_L29N_0	B12	I/O
0	IO_L29P_0	A12	I/O
0	IO_L30N_0	C12	I/O
0	IO_L30P_0	D13	I/O
0	IO_L31N_0	F12	I/O
0	IO_L31P_0	E12	I/O
0	IO_L32N_0/VREF_0	D11	VREF
0	IO_L32P_0	C11	I/O
0	IO_L33N_0	B10	I/O
0	IO_L33P_0	A10	I/O

Table 87: Spartan-3A FG676 Pinout(Continued)

Bank	Pin Name	FG676 Ball	Type
3	IO_L30P_3	N5	I/O
3	IO_L31N_3	N2	I/O
3	IO_L31P_3	N1	I/O
3	IO_L32N_3/LHCLK1	N7	LHCLK
3	IO_L32P_3/LHCLK0	N6	LHCLK
3	IO_L33N_3/IRDY2/LHCLK3	P2	LHCLK
3	IO_L33P_3/LHCLK2	P1	LHCLK
3	IO_L34N_3/LHCLK5	P3	LHCLK
3	IO_L34P_3/LHCLK4	P4	LHCLK
3	IO_L35N_3/LHCLK7	P10	LHCLK
3	IO_L35P_3/TRDY2/LHCLK6	N9	LHCLK
3	IO_L36N_3	R2	I/O
3	IO_L36P_3/VREF_3	R1	VREF
3	IO_L37N_3	R4	I/O
3	IO_L37P_3	R3	I/O
3	IO_L38N_3	T4	I/O
3	IO_L38P_3	T3	I/O
3	IO_L39N_3	P6	I/O
3	IO_L39P_3	P7	I/O
3	IO_L40N_3	R6	I/O
3	IO_L40P_3	R5	I/O
3	IO_L41N_3	P9	I/O
3	IO_L41P_3	P8	I/O
3	IO_L42N_3	U4	I/O
3	IO_L42P_3	T5	I/O
3	IO_L43N_3	R9	I/O
3	IO_L43P_3/VREF_3	R10	VREF
3	IO_L44N_3	U2	I/O
3	IO_L44P_3	U1	I/O
3	IO_L45N_3	R7	I/O
3	IO_L45P_3	R8	I/O
3	IO_L47N_3	V2	I/O
3	IO_L47P_3	V1	I/O
3	IO_L48N_3	T9	I/O
3	IO_L48P_3	T10	I/O
3	IO_L49N_3	V5	I/O
3	IO_L49P_3	U5	I/O
3	IO_L51N_3	U6	I/O
3	IO_L51P_3	T7	I/O
3	IO_L52N_3	W4	I/O

Table 87: Spartan-3A FG676 Pinout(Continued)

Bank	Pin Name	FG676 Ball	Type
3	IO_L52P_3	W3	I/O
3	IO_L53N_3	Y2	I/O
3	IO_L53P_3	Y1	I/O
3	IO_L55N_3	AA3	I/O
3	IO_L55P_3	AA2	I/O
3	IO_L56N_3	U8	I/O
3	IO_L56P_3	U7	I/O
3	IO_L57N_3	Y6	I/O
3	IO_L57P_3	Y5	I/O
3	IO_L59N_3	V6	I/O
3	IO_L59P_3	V7	I/O
3	IO_L60N_3	AC1	I/O
3	IO_L60P_3	AB1	I/O
3	IO_L61N_3	V8	I/O
3	IO_L61P_3	U9	I/O
3	IO_L63N_3	W6	I/O
3	IO_L63P_3	W7	I/O
3	IO_L64N_3	AC3	I/O
3	IO_L64P_3	AC2	I/O
3	IO_L65N_3	AD2	I/O
3	IO_L65P_3	AD1	I/O
3	IP_L04N_3/VREF_3	C1	VREF
3	IP_L04P_3	C2	INPUT
3	IP_L08N_3	D1	INPUT
3	IP_L08P_3	D2	INPUT
3	IP_L12N_3/VREF_3	H4	VREF
3	IP_L12P_3	G5	INPUT
3	IP_L16N_3	G1	INPUT
3	IP_L16P_3	G2	INPUT
3	IP_L20N_3/VREF_3	J2	VREF
3	IP_L20P_3	J3	INPUT
3	IP_L24N_3	K1	INPUT
3	IP_L24P_3	J1	INPUT
3	IP_L46N_3	V4	INPUT
3	IP_L46P_3	U3	INPUT
3	IP_L50N_3/VREF_3	W2	VREF
3	IP_L50P_3	W1	INPUT
3	IP_L54N_3	Y4	INPUT
3	IP_L54P_3	Y3	INPUT
3	IP_L58N_3/VREF_3	AA5	VREF

